

TIDA-00509 16-Button Inductive Keypad BOM for PCB Rev2, March 6, 2015							
Item	Qty	Digikey PN	Part Reference	Value	Description	MFG1	MFG1_PN
1	16	490-3229-1-ND	C1 C2 C3 C4 C5 C6 C7 C8 C9 C10 C11 C12 C13 C14 C15 C16	150pF	CAP,0402,NPO,150pF,+/-5%, 50V -55~125C	muRata	GRM1555C1H151JA01D
2	2	587-1451-1-ND	C17 C18	0.1uF	CAP,0402,X7R,0.1uF,+/-10%, 16V, -55~125C	Taiyo Yuden	EMK105B7104KV-F
3	2	S6008-08-ND	J1 J2	HEADER 8X2	8X2 2MM SMD HEADER H=2.2MM Peg=1.2MM	Sullins	NRPN082MAMP-RC
5	4	952-2179-ND	M1 M2 M3 M4	SPACER	HEX STANDOFF M3 Brass/Nickle 5MM F-F	Harwin Inc	R30-1000502
6	4		M5 M6 M7 M8	M3X4 Stainless Steel Flat, 100 piece	M3x4mm Stainless Steel Flat Head Machine Screw, 100-piece	www.laptopscrews.com/M3x4.htm	Item #10109
7	2	FSUSB74UMXCT-ND	U1 U2	FSUSB74	Analog SW 2X4:1 - 40~85C 2.7-4.4V 6.5 Ohm 7.5p/2p	Fairchild Semi	FSUSB74UMX

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